ON Semiconductor®



Final Product/Process Change Notification Document # : FPCN20930XB1 Issue Date: 3 May 2018

Title of Change:	Update to FPCN20930XB - Qualification of Power Schottky Die-Shrink for DPAK, SO8 FL and TO-220 Package					
Proposed first ship date:	14 June 2018					
Contact information:	Contact your local ON Semiconductor Sales Office or <sitinurhaza.mohdramli@onsemi.com></sitinurhaza.mohdramli@onsemi.com>					
Samples:	Contact your local ON Semiconductor Sales Office or <pcn.samples@onsemi.com></pcn.samples@onsemi.com>					
Additional Reliability Data:	Contact your local	ON Sem	iconductor Sales Office	e or <mohdazizi< th=""><th>.Azman@</th><th>onsemi.com></th></mohdazizi<>	.Azman@	onsemi.com>
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>					
Change Part Identification:	There will be no change in the device marking scheme. Clean date code will be advised as requested.				ll be advised as requested.	
Change category:	Wafer Fab Change Assembly Change Test Change Other					
Change Sub-Category(s): Manufacturing Site Change Manufacturing Process Change 						
Sites Affected:	ON Semiconductor Sites: ON ISMF, Malaysia ON Seremban, Malaysia ON Dong Nai Province, Vietnam			External Foundry/Subcon Sites: Tongfu Microelectronics Co.LTD (TFME)		
Description and Purpose:						
This Update Notification announces to customers that ON Binh Duong Province, Vietnam will be removed from the Sites Affected list of FPCN20930XB and list ON Dong Nai Province, Vietnam as the correct assembly site affected.						
ON Binh Duong Province, Vietnam is removed from FPCN20930XB because this site is for DBC manufacturing and not affected by Power Schottky die shrink -guard ring width changes.						
The other information in FPCN20930XB remains the same as below:						
Material to be changed		Before Change Description			After Change Description	
Die Shrink – Guard Ring Width		4mils			1mils	
No other changes imposed on the affected OPNs. Products had gone thru reliability testing as per industrial requirements and it's proven that device performances are not affected						



Reliability Data Summary:

NRVBD660CTRLG

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=80°C, 100% max rated V	1000 hrs	0/240
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 сус	0/240
тс	JESD22-A104	Ta= - 65°C to +150°C	1000 cyc	0/240
H3TRB	JEDS22 A101	Ta=85°C RH=85% bias=80% rated V or 100V Max	1000 hrs	0/240
AC	JESD22 A102	Ta = 121°C, P= 15 PSIG, RH = 100%, 96 Hours	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/960
RSH	JESD22- B106	Ta = 265C, 10 sec		0/90

SBRB1045T4G

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=90°C, 100% max rated V	1000 hrs	0/240
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	8572 сус	0/240
тс	JESD22-A104	Ta= - 65°C to +150°C	1000 cyc	0/240
H3TRB	JEDS22 A101	Ta=85°C RH=85% bias=80% rated V or 100V Max	1000 hrs	0/240
AC	JESD22 A102	Ta = 121°C, P= 15 PSIG, RH = 100%, 96 Hours	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		0/960
RSH	JESD22- B106	Ta = 265C, 10 sec		0/90

Electrical Characteristic Summary:

There are no changes in electrical characteristic; product performance meets data sheet specifications. Characterization data is available upon request



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List of Affected Standard Parts:	
Part Number	Qualification Vehicle
MBR440MFST1G	
MBR440MFST3G	
MBR460MFST1G	
MBR460MFST3G	
MBRD1035CTLG	
MBRD1035CTLT4G	
MBRD620CTT4G	
MBRD630CTT4G	
MBRD640CTG	
MBRD640CTT4G	
MBRD640CTT4H	
MBRD650CTG	
MBRD650CTT4G	
MBRD660CTG	
MBRD660CTRLG	
MBRD660CTT4G	
MBRD660CTT4H	NRVBD660CTRLG
MBR560MFST1G	
MBR560MFST3G	
MBR1060G	
MBRD320G	
MBRD320RLG	
MBRD320RLH	
MBRD320T4G	
MBRD320T4H	
MBRD330G	
MBRD330RLG	
MBRD330T4G	
MBRD340G	
MBRD340RLG	
MBRD340T4G	
MBRD350G	

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Final Product/Process Change Notification Document # : FPCN20930XB1 Issue Date: 3 May 2018

Part Number	Qualification Vehicle	
MBRD350RLG		
MBRD350T4G	NRVBD660CTRLG	
MBRD360G		
MBRD360RLG		
MBRD360T4G		
MBR1035G		
MBR1045G		
MBR1045H		
MBR830MFST1G		
MBR830MFST3G	SBRB1045T4G	
MBR860MFST1G		
MBR860MFST3G		
MBRD1045T4G	1	